

FAMILY OF MICROPOWER RAIL-TO-RAIL INPUT AND OUTPUT OPERATIONAL AMPLIFIERS

FEATURES

- **BiMOS Rail-to-Rail Input/Output**
- **Input Bias Current . . . 1 pA**
- **High Wide Bandwidth . . . 160 kHz**
- **High Slew Rate . . . 0.1 V/μs**
- **Supply Current . . . 7 μA (per channel)**
- **Input Noise Voltage . . . 90 nV/√Hz**
- **Supply Voltage Range . . . 2.7 V to 16 V**
- **Specified Temperature Range**
 - –40°C to 125°C . . . Industrial Grade
- **Ultra-Small Packaging**
 - 5 Pin SOT-23 (TLV2381)

APPLICATIONS

- **Portable Medical**
- **Power Monitoring**
- **Low Power Security Detection Systems**
- **Smoke Detectors**

DESCRIPTION

The TLV238x single supply operational amplifiers provide rail-to-rail input and output capability. The TLV238x takes the minimum operating supply voltage down to 2.7 V over the extended industrial temperature range, while adding the rail-to-rail output swing feature. The TLV238x also provides 160-kHz bandwidth from only 7 μA. The maximum recommended supply voltage is 16 V, which allows the devices to be operated from (±8 V supplies down to ±1.35 V) two rechargeable cells.

The combination of rail-to-rail inputs and outputs make them good upgrades for the TLC27Lx family—offering more bandwidth at a lower quiescent current. The offset voltage is lower than the TLC27LxA variant.

To maintain cost effectiveness the TLV2381/2 are only available in the extended industrial temperature range. This means that one device can be used in a wide range of applications that include PDAs as well as automotive sensor interface.

All members are available in SOIC, with the singles in the small SOT-23 package, duals in the MSOP.

SELECTION GUIDE

| DEVICE | V _S [V] | I _Q /ch [μA] | V _{ICR} [V] | V _{IO} [mV] | I _{IB} [pA] | GBW [MHz] | SLEW RATE [V/μs] | V _n , 1 kHz [nV/√Hz] |
|---------|-----------------------|----------------------------|------------------------------|-------------------------|-------------------------|--------------|---------------------|------------------------------------|
| TLV238x | 2.7 to 16 | 10 | -0.2 to V _S + 0.2 | 4.5 | 60 | 0.16 | 0.06 | 100 |
| TLV27Lx | 2.7 to 16 | 11 | -0.2 to V _S - 1.2 | 5 | 60 | 0.16 | 0.06 | 100 |
| TLC27Lx | 4 to 16 | 17 | -0.2 to V _S - 1.5 | 10/5/2 | 60 | 0.085 | 0.03 | 68 |
| OPAx349 | 1.8 to 5.5 | 2 | -0.2 to V _S + 0.2 | 10 | 10 | 0.070 | 0.02 | 300 |
| OPAx347 | 2.3 to 5.5 | 34 | -0.2 to V _S + 0.2 | 6 | 10 | 0.35 | 0.01 | 60 |
| TLC225x | 2.7 to 16 | 62.5 | 0 to V _S - 1.5 | 1.5/0.85 | 60 | 0.200 | 0.02 | 19 |

NOTE: All dc specs are maximums while ac specs are typicals.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PACKAGE/ORDERING INFORMATION

| PRODUCT | PACKAGE | PACKAGE CODE | SYMBOL | SPECIFIED TEMPERATURE RANGE | ORDER NUMBER | TRANSPORT MEDIA |
|-------------|---------|--------------|--------|-----------------------------|--------------|-----------------|
| TLV2381ID | SOIC-8 | D | 2381I | -40°C to 125°C | TLV2381ID | Tube |
| | | | | | TLV2381IDR | Tape and Reel |
| TLV2381IDBV | SOT-23 | DBV | VBKI | | TLV2381IDBVR | Tape and Reel |
| | | | | | TLV2381IDBVT | |
| TLV2382ID | SOIC-8 | D | 2382I | | TLV2382ID | Tube |
| | | | | | TLV2382IDR | Tape and Reel |

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

| | |
|--|------------------------------|
| Supply voltage, V_S | 16.5 V |
| Input voltage, V_I (see Notes 1 and 2) | $V_S + 0.2 V$ |
| Output current, I_O | 100 mA |
| Differential input voltage, V_{ID} | V_S |
| Continuous total power dissipation | See Dissipation Rating Table |
| Maximum junction temperature, T_J | 150°C |
| Operating free-air temperature range, T_A : I suffix | -40°C to 125°C |
| Storage temperature range, T_{stg} | -65°C to 125°C |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 300°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Relative to GND pin.
2. Maximum is 16.5 V or $V_S+0.2 V$ whichever is the lesser value.

DISSIPATION RATING TABLE

| PACKAGE | θ_{JC} (°C/W) | θ_{JA} (°C/W) | $T_A \leq 25^\circ\text{C}$ POWER RATING | $T_A = 85^\circ\text{C}$ POWER RATING |
|---------|-------------------------|-------------------------|---|--|
| D (8) | 38.3 | 176 | 710 mW | 370 mW |
| DBV (5) | 55 | 324.1 | 385 mW | 201 mW |
| DBV (6) | 55 | 294.3 | 425 mW | 221 mW |

recommended operating conditions

| | | MIN | MAX | UNIT |
|--|---------------|-------|---------------------|------|
| Supply voltage, (V _S) | Dual supply | ±1.35 | ±8 | V |
| | Single supply | 2.7 | 16 | |
| Input common-mode voltage range | | -0.2 | V _S +0.2 | V |
| Operating free air temperature, T _A | I-suffix | -40 | 125 | °C |

electrical characteristics at recommended operating conditions, V_S = 2.7 V, 5 V, and 15 V (unless otherwise noted)

dc performance

| PARAMETER | | TEST CONDITIONS | | T _A † | MIN | TYP | MAX | UNIT |
|------------------|---|--|---|------------------|-----|-----|-----|-------|
| V _{IO} | Input offset voltage | V _{IC} = V _S /2, R _L = 100 kΩ | V _O = V _S /2 R _S = 50 Ω | 25°C | 0.5 | 4.5 | 6.5 | mV |
| | | | | Full range | | | | |
| α _{VIO} | Offset voltage drift | | | 25°C | 1.1 | | | μV/°C |
| CMRR | Common-mode rejection ratio | V _{IC} = 0 V to V _S , R _S = 50 Ω | V _S = 2.7 V | 25°C | 54 | 69 | 70 | dB |
| | | | | Full range | 53 | | | |
| | | | | 25°C | 71 | 86 | | |
| | | | | Full range | 70 | | | |
| | | V _{IC} = 0 V to V _S , R _S = 50 Ω | V _S = 5 V | 25°C | 58 | 74 | 70 | dB |
| | | | | Full range | 57 | | | |
| | | | | 25°C | 72 | 88 | | |
| | | | | Full range | 70 | | | |
| | | V _{IC} = 0 V to V _S , R _S = 50 Ω | V _S = 15 V | 25°C | 65 | 80 | 70 | dB |
| | | | | Full range | 64 | | | |
| | | | | 25°C | 72 | 90 | | |
| | | | | Full range | 70 | | | |
| A _{VD} | Large-signal differential voltage amplification | V _{O(PP)} = V _S /2, R _L = 100 kΩ | V _S = 2.7 V | 25°C | 80 | 100 | 77 | dB |
| | | | | Full range | 77 | | | |
| | | | V _S = 5 V | 25°C | 80 | 100 | 77 | |
| | | | | Full range | 77 | | | |
| | | | V _S = 15 V | 25°C | 77 | 83 | 74 | |
| | | | | Full range | 74 | | | |

† Full range is -40°C to 125°C.

input characteristics

| PARAMETER | | TEST CONDITIONS | | T _A | MIN | TYP | MAX | UNIT |
|-------------------|-------------------------------|---|--|----------------|------|-----|------|------|
| I _{IO} | Input offset current | V _{IC} = V _S /2, R _L = 100 kΩ , | V _O = V _S /2, R _S = 50 Ω | ≤25°C | 1 | | 60 | pA |
| | | | | ≤70°C | | | 100 | |
| | | | | ≤125°C | | | 1000 | |
| | | | | ≤25°C | 1 | | 60 | |
| I _{IB} | Input bias current | | | ≤25°C | 1 | | 60 | pA |
| | | | | ≤70°C | | | 200 | |
| | | | | ≤125°C | | | 1000 | |
| r _{i(d)} | Differential input resistance | | | 25°C | 1000 | | GΩ | |
| C _{IC} | Common-mode input capacitance | f = 1 kHz | | 25°C | 8 | | pF | |

electrical characteristics at recommended operating conditions, $V_S = 2.7\text{ V}$, 5 V , and 15 V (unless otherwise noted) (continued)

power supply

| PARAMETER | | TEST CONDITIONS | T_A † | MIN | TYP | MAX | UNIT |
|-----------|---|--|------------|-----|-----|-----|---------------|
| I_{DD} | Supply current (per channel) | $V_O = V_S/2$ | 25°C | 7 | 10 | | μA |
| | | | Full range | | 15 | | |
| PSRR | Power supply rejection ratio ($\Delta V_S/\Delta V_{IO}$) | $V_S = 2.7\text{ V}$ to 16 V , $V_{IC} = V_S/2\text{ V}$ | 25°C | 74 | 82 | | dB |
| | | | Full range | 70 | | | |

† Full range is -40°C to 125°C for I suffix.

output characteristics

| PARAMETER | | TEST CONDITIONS | T_A † | MIN | TYP | MAX | UNIT |
|---------------------|--------------------------------|--|----------------------|------------|-----|-----|---------------|
| V_O | Output voltage swing from rail | $V_{IC} = V_S/2$, $I_O = 100\ \mu\text{A}$ | $V_S = 2.7\text{ V}$ | 25°C | 200 | 160 | mV |
| | | | | Full range | 220 | | |
| | | | $V_S = 5\text{ V}$ | 25°C | 120 | 85 | |
| | | | | Full range | 200 | | |
| | | $V_S = 15\text{ V}$ | 25°C | 120 | 50 | | |
| | | | Full range | 150 | | | |
| | | $V_{IC} = V_S/2$, $I_O = 500\ \mu\text{A}$ | $V_S = 5\text{ V}$ | 25°C | 800 | 420 | mV |
| | | | | Full range | 900 | | |
| $V_S = 15\text{ V}$ | 25°C | | 400 | 200 | | | |
| | Full range | | 500 | | | | |
| I_O | Output current | $V_O = 0.5\text{ V}$ from rail | $V_S = 2.7\text{ V}$ | 25°C | 400 | | μA |

† Full range is -40°C to 125°C for I suffix.

dynamic performance

| PARAMETER | | TEST CONDITIONS | T_A | MIN | TYP | MAX | UNIT |
|-----------|-------------------------|--|---------------------|------|------|-----|------------------------|
| GBP | Gain bandwidth product | $R_L = 100\ \text{k}\Omega$, $C_L = 10\ \text{pF}$, $f = 1\ \text{kHz}$ | 25°C | | 160 | | kHz |
| SR | Slew rate at unity gain | $V_{O(pp)} = 2\ \text{V}$, $R_L = 100\ \text{k}\Omega$, $C_L = 10\ \text{pF}$ | 25°C | | 0.06 | | $\text{V}/\mu\text{s}$ |
| | | | -40°C | | 0.05 | | |
| | | | 125°C | | 0.08 | | |
| ϕ_M | Phase margin | $R_L = 100\ \text{k}\Omega$, $C_L = 50\ \text{pF}$ | 25°C | | 62 | | $^\circ$ |
| | Gain margin | | 25°C | | 6.7 | | dB |
| t_s | Settling time (0.1%) | $V_{(STEP)pp} = 1\ \text{V}$, $A_V = -1$, $C_L = 10\ \text{pF}$, $R_L = 100\ \text{k}\Omega$ | 25°C | Rise | 31 | | μs |
| | | | | Fall | 61 | | |

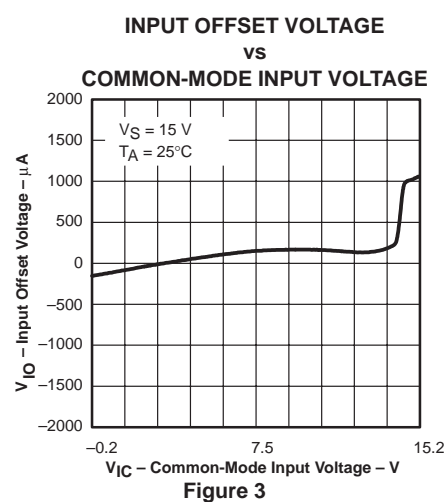
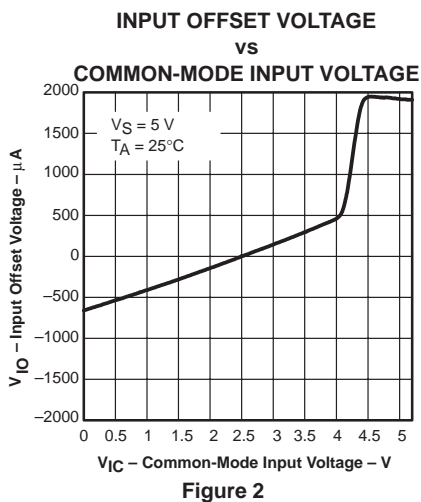
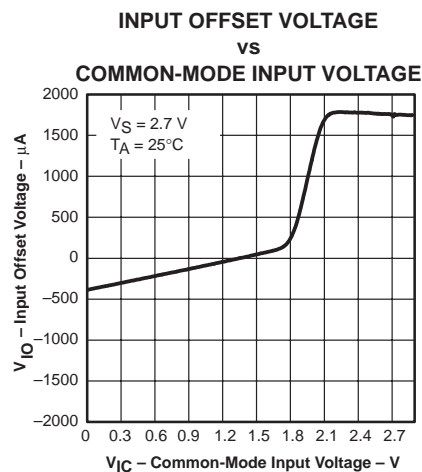
noise/distortion performance

| PARAMETER | | TEST CONDITIONS | T_A | MIN | TYP | MAX | UNIT |
|-----------|--------------------------------|---------------------|-------|-----|-----|-----|------------------------------|
| V_n | Equivalent input noise voltage | $f = 1\ \text{kHz}$ | 25°C | | 90 | | $\text{nV}/\sqrt{\text{Hz}}$ |

TYPICAL CHARACTERISTICS

Table of Graphs

| | | | FIGURE |
|---|---|------------------------------|----------|
| V_{IO} | Input offset voltage | vs Common-mode input voltage | 1, 2, 3 |
| I_{IB}/I_{IO} | Input bias and offset current | vs Free-air temperature | 4 |
| V_{OH} | High-level output voltage | vs High-level output current | 5, 7, 9 |
| V_{OL} | Low-level output voltage | vs Low-level output current | 6, 8, 10 |
| I_Q | Quiescent current | vs Supply voltage | 11 |
| | | vs Free-air temperature | 12 |
| Supply voltage and supply current ramp up | | | 13 |
| A_{VD} | Differential voltage gain and phase shift | vs Frequency | 14 |
| GBP | Gain-bandwidth product | vs Free-air temperature | 15 |
| ϕ_m | Phase margin | vs Load capacitance | 16 |
| CMRR | Common-mode rejection ratio | vs Frequency | 17 |
| PSRR | Power supply rejection ratio | vs Frequency | 18 |
| | Input referred noise voltage | vs Frequency | 19 |
| SR | Slew rate | vs Free-air temperature | 20 |
| $V_{O(PP)}$ | Peak-to-peak output voltage | vs Frequency | 21 |
| | Inverting small-signal response | | 22 |
| | Inverting large-signal response | | 23 |
| | Crosstalk | vs Frequency | 24 |



TYPICAL CHARACTERISTICS

INPUT BIAS AND INPUT
OFFSET CURRENT
VS
FREE-AIR TEMPERATURE

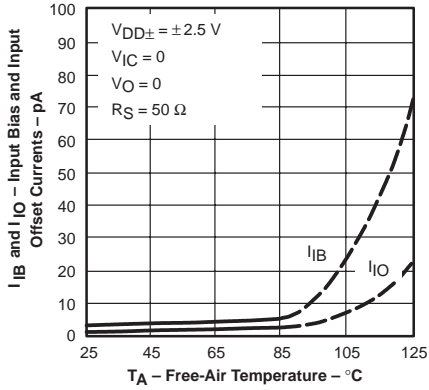


Figure 4

HIGH-LEVEL OUTPUT VOLTAGE
VS
HIGH-LEVEL OUTPUT CURRENT

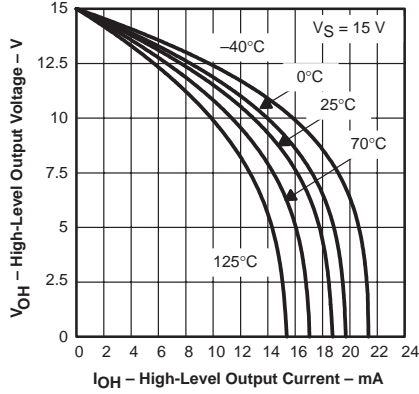


Figure 5

LOW-LEVEL OUTPUT VOLTAGE
VS
LOW-LEVEL OUTPUT CURRENT

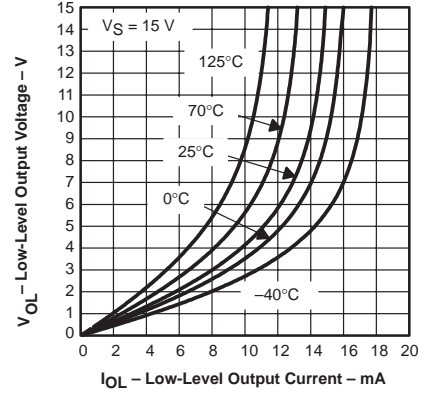


Figure 6

HIGH-LEVEL OUTPUT VOLTAGE
VS
HIGH-LEVEL OUTPUT CURRENT

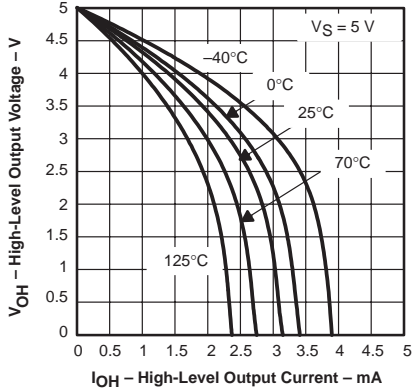


Figure 7

LOW-LEVEL OUTPUT VOLTAGE
VS
LOW-LEVEL OUTPUT CURRENT

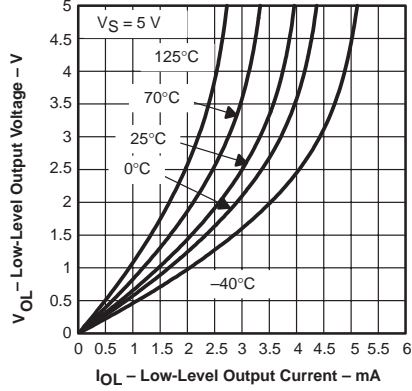


Figure 8

HIGH-LEVEL OUTPUT VOLTAGE
VS
HIGH-LEVEL OUTPUT CURRENT

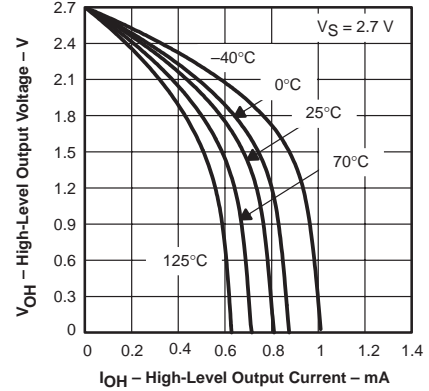


Figure 9

LOW-LEVEL OUTPUT VOLTAGE
VS
LOW-LEVEL OUTPUT CURRENT

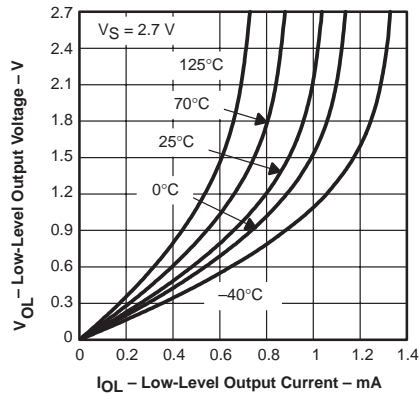


Figure 10

QUIESCENT CURRENT
VS
SUPPLY VOLTAGE

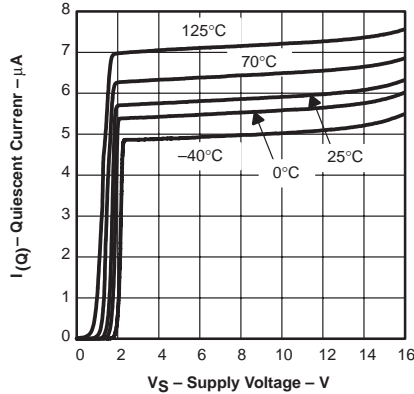


Figure 11

QUIESCENT CURRENT
VS
FREE-AIR TEMPERATURE

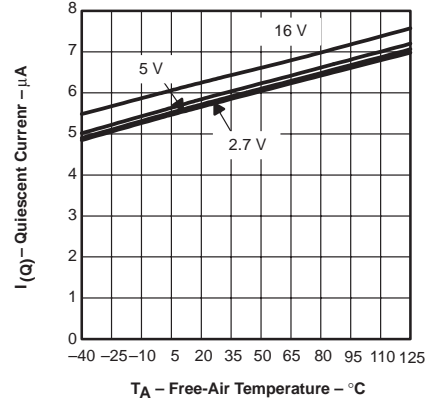


Figure 12

TYPICAL CHARACTERISTICS

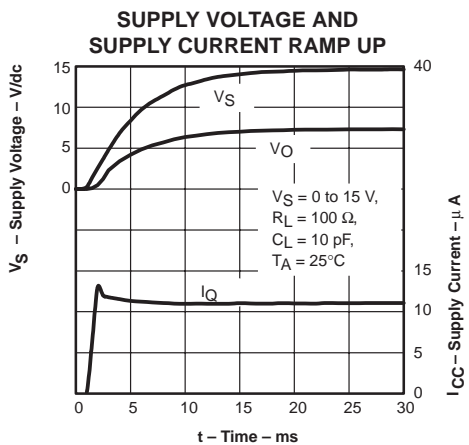


Figure 13

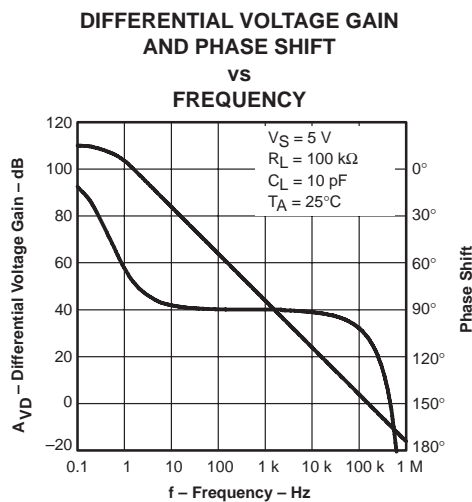


Figure 14

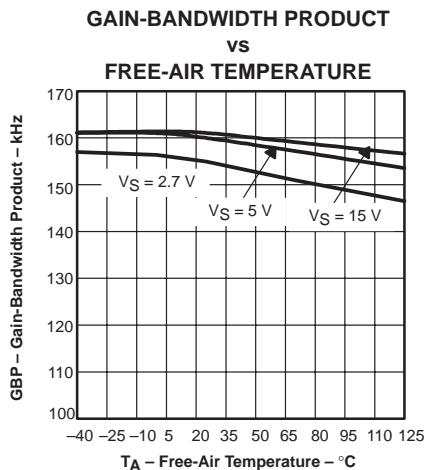


Figure 15

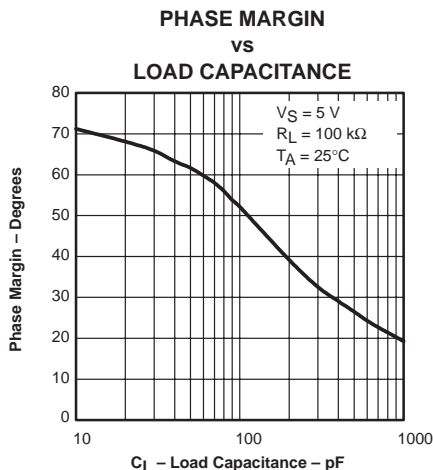


Figure 16

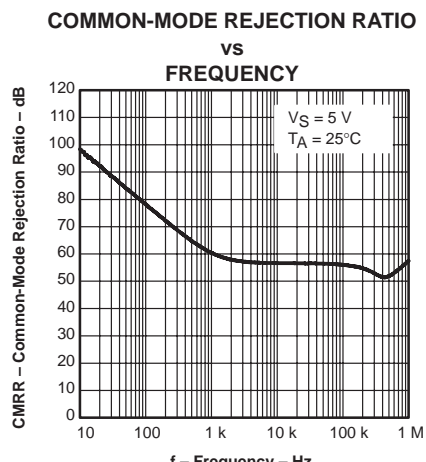


Figure 17

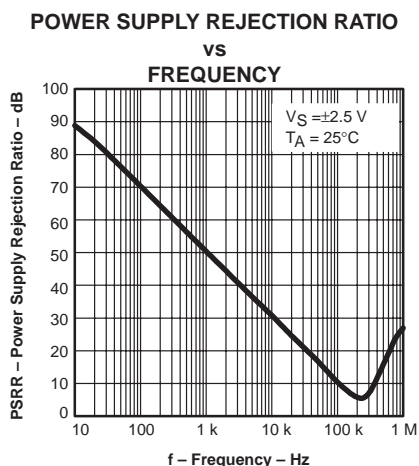


Figure 18

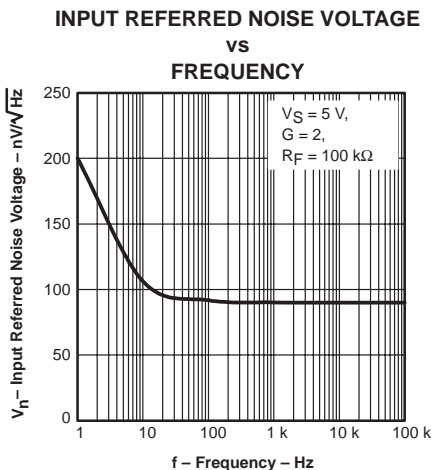


Figure 19

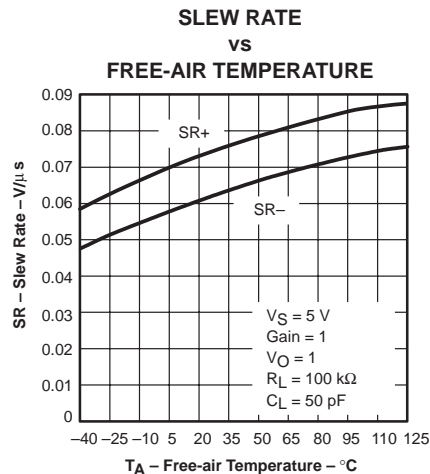
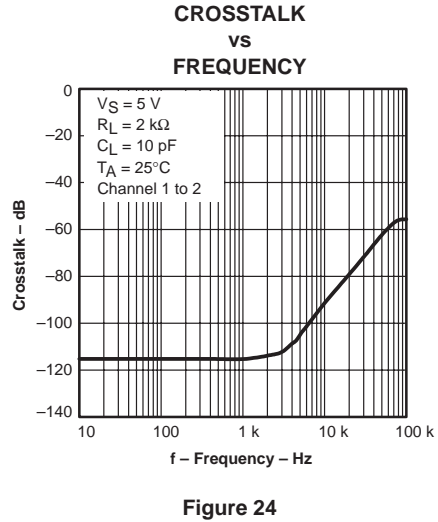
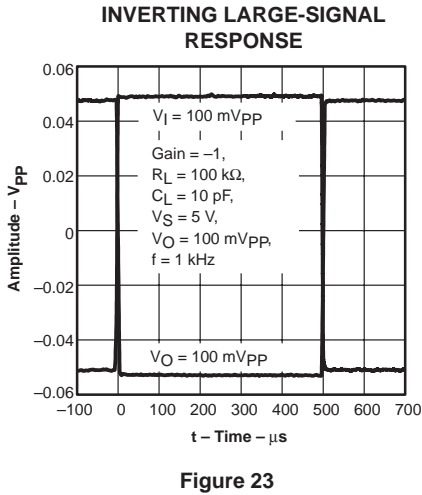
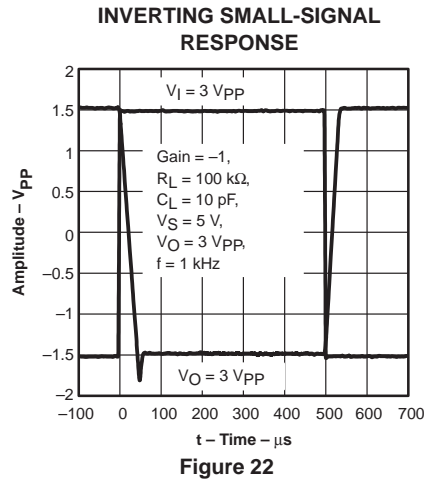
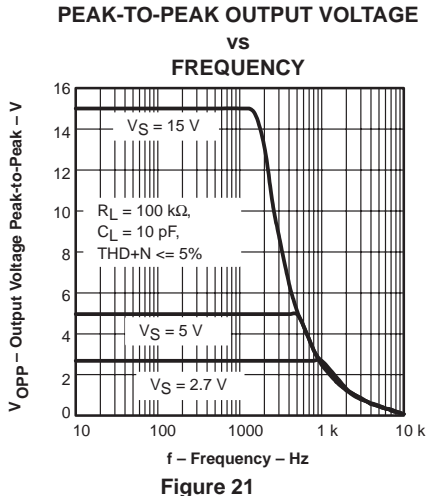


Figure 20

TYPICAL CHARACTERISTICS



APPLICATION INFORMATION

offset voltage

The output offset voltage (V_{OO}) is the sum of the input offset voltage (V_{IO}) and both input bias currents (I_{IB}) times the corresponding gains. The following schematic and formula can be used to calculate the output offset voltage:

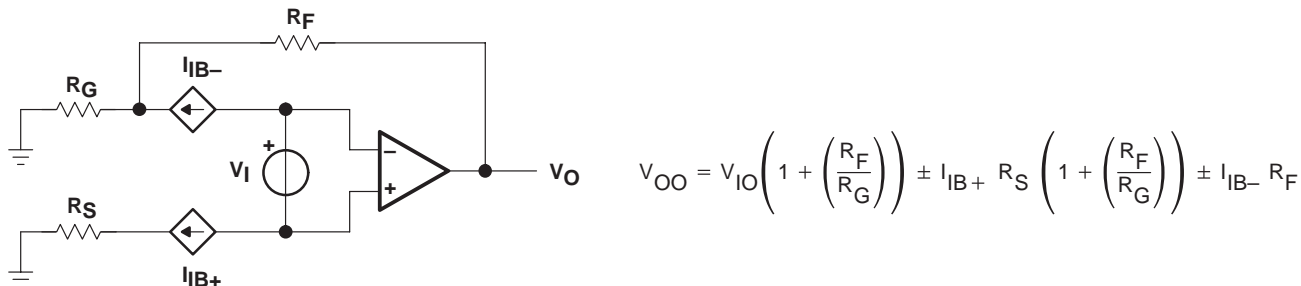


Figure 25. Output Offset Voltage Model

general configurations

When receiving low-level signals, limiting the bandwidth of the incoming signals into the system is often required. The simplest way to accomplish this is to place an RC filter at the noninverting terminal of the amplifier (see Figure 26).

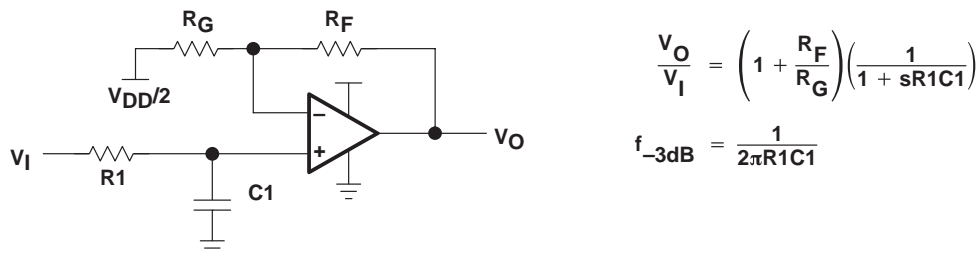


Figure 26. Single-Pole Low-Pass Filter

If even more attenuation is needed, a multiple pole filter is required. The Sallen-Key filter can be used for this task. For best results, the amplifier should have a bandwidth that is 8 to 10 times the filter frequency bandwidth. Failure to do this can result in phase shift of the amplifier.

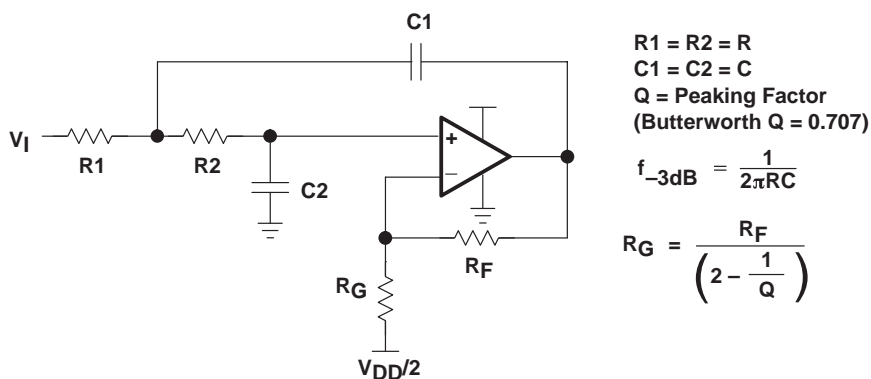


Figure 27. 2-Pole Low-Pass Sallen-Key Filter

APPLICATION INFORMATION

circuit layout considerations

To achieve the levels of high performance of the TLV238x, follow proper printed-circuit board design techniques. A general set of guidelines is given in the following.

- Ground planes—It is highly recommended that a ground plane be used on the board to provide all components with a low inductive ground connection. However, in the areas of the amplifier inputs and output, the ground plane can be removed to minimize the stray capacitance.
- Proper power supply decoupling—Use a 6.8- μ F tantalum capacitor in parallel with a 0.1- μ F ceramic capacitor on each supply terminal. It may be possible to share the tantalum among several amplifiers depending on the application, but a 0.1- μ F ceramic capacitor should always be used on the supply terminal of every amplifier. In addition, the 0.1- μ F capacitor should be placed as close as possible to the supply terminal. As this distance increases, the inductance in the connecting trace makes the capacitor less effective. The designer should strive for distances of less than 0.1 inches between the device power terminals and the ceramic capacitors.
- Sockets—Sockets can be used but are not recommended. The additional lead inductance in the socket pins will often lead to stability problems. Surface-mount packages soldered directly to the printed-circuit board is the best implementation.
- Short trace runs/compact part placements—Optimum high performance is achieved when stray series inductance has been minimized. To realize this, the circuit layout should be made as compact as possible, thereby minimizing the length of all trace runs. Particular attention should be paid to the inverting input of the amplifier. Its length should be kept as short as possible. This will help to minimize stray capacitance at the input of the amplifier.
- Surface-mount passive components—Using surface-mount passive components is recommended for high performance amplifier circuits for several reasons. First, because of the extremely low lead inductance of surface-mount components, the problem with stray series inductance is greatly reduced. Second, the small size of surface-mount components naturally leads to a more compact layout thereby minimizing both stray inductance and capacitance. If leaded components are used, it is recommended that the lead lengths be kept as short as possible.

APPLICATION INFORMATION

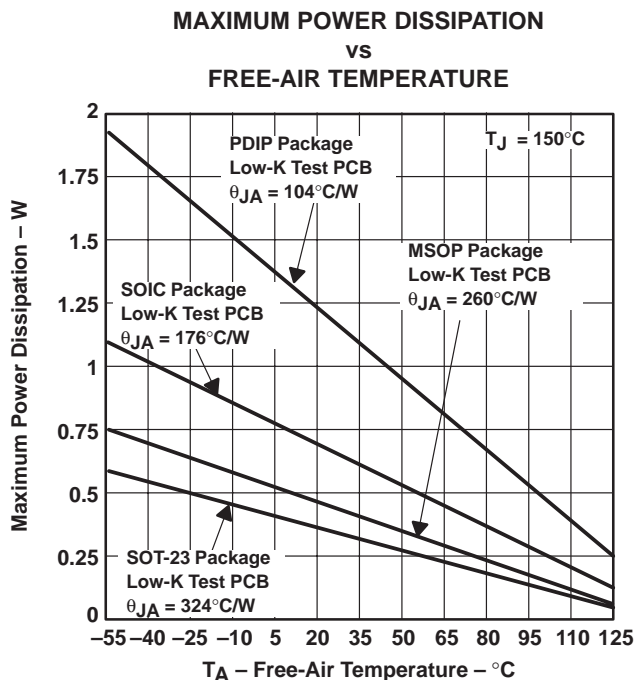
general power dissipation considerations

For a given θ_{JA} , the maximum power dissipation is shown in Figure 28 and is calculated by the following formula:

$$P_D = \left(\frac{T_{MAX} - T_A}{\theta_{JA}} \right)$$

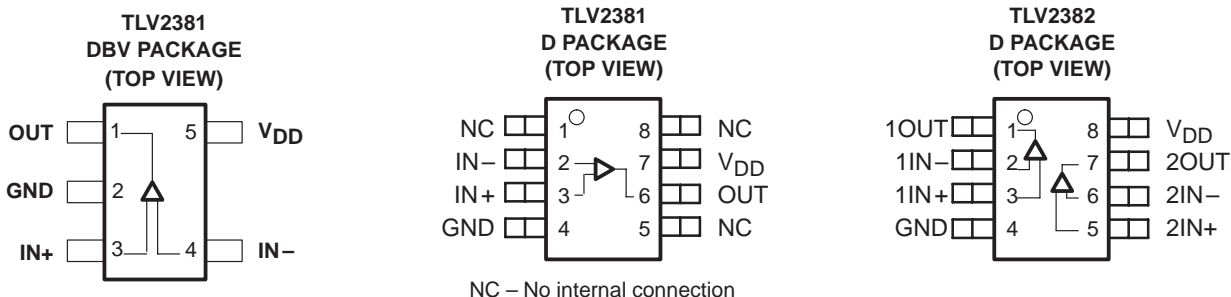
Where:

- P_D = Maximum power dissipation of TLV238x IC (watts)
- T_{MAX} = Absolute maximum junction temperature (150°C)
- T_A = Free-ambient air temperature (°C)
- θ_{JA} = $\theta_{JC} + \theta_{CA}$
- θ_{JC} = Thermal coefficient from junction to case
- θ_{CA} = Thermal coefficient from case to ambient air (°C/W)



NOTE A: Results are with no air flow and using JEDEC Standard Low-K test PCB.

Figure 28. Maximum Power Dissipation vs Free-Air Temperature



PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| TLV2381ID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2381IDBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2381IDBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2381IDBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2381IDBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2381IDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2381IDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2381IDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2381IP | PREVIEW | PDIP | P | 8 | | TBD | Call TI | Call TI |
| TLV2382ID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2382IDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2382IDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2382IDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TLV2382IP | OBSOLETE | PDIP | P | 8 | | TBD | Call TI | Call TI |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TLV2381IDBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 9.0 | 3.15 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TLV2381IDBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 9.0 | 3.15 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TLV2381IDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TLV2382IDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TLV2381IDBVR | SOT-23 | DBV | 5 | 3000 | 182.0 | 182.0 | 20.0 |
| TLV2381IDBVT | SOT-23 | DBV | 5 | 250 | 182.0 | 182.0 | 20.0 |
| TLV2381IDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| TLV2382IDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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